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The fabrication of integrated circuit (IC) chips or die is a complex and important process that allows the desired electrical connections between billions of transistors on a single chip to be formed. In the past, the actual semiconductor material used was silicon. However, it was discovered that increasing the size of the channel region of a field effect transistor allowed for higher speed performance with increasingly smaller device sizes. Since the discovery of silicon as an appropriate semiconductor material, other materials have been used in semiconductor fabrication, including gallium arsenide, cadmium arsenide, indium phosphide, gallium nitride, silicon germanium and various other semi-conductor materials. Silicon was chosen as a base semiconductor because it is the most common semiconductor material, is relatively low in cost, and has excellent electrical properties. As used in the semiconductor industry, the term “die” is a wafer substrate, usually made of silicon or gallium arsenide, on which one or more layers of conducting, semiconducting, dielectric and/or optoelectronic materials have been deposited and the materials utilized to form transistors and other circuit elements. Circuit elements formed in a die may be interconnected on the die through one or more “bond” pads on the die to locations in the die containing contacts (i.e., bond pads). These contacts may be formed as electrically conductive structures formed in one or more “metallization layers” formed in the die. These contacts, and the metallization layers utilized to provide interconnectivity between contacts, are often referred to as “wiring” or “metallization” between one or more die and/or one or more packages to which the die is connected. In a typical die, bonding pads may be formed on the surface of the die near a periphery of a substrate surface. Bonding pads are typically used to make electrical connections between the die and a package that is connected to the die using wire bonds or other conductive structures. In many types of integrated circuits, multiple die are bonded together to form a multi-chip package. Prior to bonding the die to the package, a thin layer of insulating material, such as an oxide or polyimide

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